



Product / Package Information	
Package	LGA_CAV
Body Size (mm)	3.35 X 2.5 X 0.88
Ball Count	3
Terminal Finish	Gold

Environmental Information	
RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

**Materials Declaration**

Lid/Shield								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	PPM
Stainless steel	Iron	7439-89-6	4.61 E-03	68.84	688402	29.35		293517
Stainless steel	Chromium	7440-47-3	1.16 E-03	17.31	173057	7.38		73787
Stainless steel	Nickel	7440-02-0	5.19 E-04	7.74	77445	3.30		33021
Stainless steel	Manganese	7439-96-5	8.14 E-05	1.21	12143	0.52		5177
Stainless steel	Silicon	7440-21-3	3.33 E-05	0.50	4972	0.21		2120
Stainless steel	Carbon	7440-44-0	3.14 E-06	0.05	468	0.02		200
Stainless steel	Phosphorus	7723-14-0	1.47 E-06	0.02	220	0.01		94
Stainless steel	Sulfur	7704-34-9	1.28 E-07	0.002	19	0.001		8
Tin & its alloys	Tin	7440-31-5	2.90 E-04	4.33	43274	1.85		18451
Subtotal			6.70 E-03	100.0	1000000	42.64		426374

Laminate								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	PPM
Composite	Laminate	Proprietary	3.52 E-03	48.16	481588	22.39		223878
Copper & its alloys	Copper	7440-50-8	1.21 E-03	16.56	165640	7.70		77002
Other organic materials	Solder Mask	Proprietary	4.42 E-04	6.05	60507	2.81		28128
Nickel & its alloys	Nickel	7440-02-0	2.05 E-03	28.12	281177	13.07		130712
Precious Metals	Gold	7440-57-5	8.10 E-05	1.11	11088	0.52		5155
Subtotal			7.31 E-03	100.00	1000000	46.49		464875

Solder Land								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	PPM
Copper & its alloys	Copper	7440-50-8	2.00 E-04	48.16	481588	1.27		12728
Nickel & its alloys	Nickel	7440-02-0	5.00 E-05	19.23	192308	0.32		3182
Precious Metals	Gold	7440-57-5	1.00 E-05	3.85	38462	0.06		636
Subtotal			2.60 E-04	100.00	1000000	1.65		16546

Bond Wires								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	PPM
Precious metals	Gold	7440-57-5	4.84 E-05	99	990000	0.31		3081
Precious metals	Palladium	7440-05-3	4.89 E-07	1	10000	0.003		31
Subtotal			4.89 E-05	100	1000000	0.31		3112

Chip								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	PPM
Other inorganic materials	Doped Silicon	7440-21-3	7.00 E-04	100	1000000	4.45		44547

Die Attach								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	PPM
Precious metals	Silver	7440-22-4	2.25 E-04	75.00	75000	1.43		14319
Other organic materials	Bisphenol F type epoxy resin	9003-36-5	3.00 E-05	10.00	100000	0.19		1909
Other organic materials	Bisphenol A type epoxy resin	25068-38-6	3.00 E-05	10.00	100000	0.19		1909
Others	Additives	Proprietary	9.00 E-06	3.00	30000	0.06		573
Others	Curing Agent	Proprietary	6.00 E-06	2.00	20000	0.04		382
Subtotal			3.00 E-04	100.00	1000000	1.91		19091

Die Coat								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	PPM
Other organic materials	Polydimethylsiloxane	Proprietary	2.00 E-04	100	1000000	1.27		12728

Lid / Shield Attach								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	PPM
Precious metals	Silver	7440-22-4	1.50 E-04	75.00	750000	0.95		9546
Other organic materials	Bisphenol F type epoxy resin	9003-36-5	2.00 E-05	10.00	100000	0.13		1273
Other organic materials	Bisphenol A type epoxy resin	25068-38-6	2.00 E-05	10.00	100000	0.13		1273
Others	Additives	Proprietary	6.00 E-06	3.00	30000	0.04		382
Others	Curing Agent	Proprietary	4.00 E-06	2.00	20000	0.03		255
Subtotal			2.00 E-04	100.00	1000000	1.27		12728

Package Totals	Weight (g)	Percentage (%)	PPM
	1.57 E-02	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.  
 ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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